

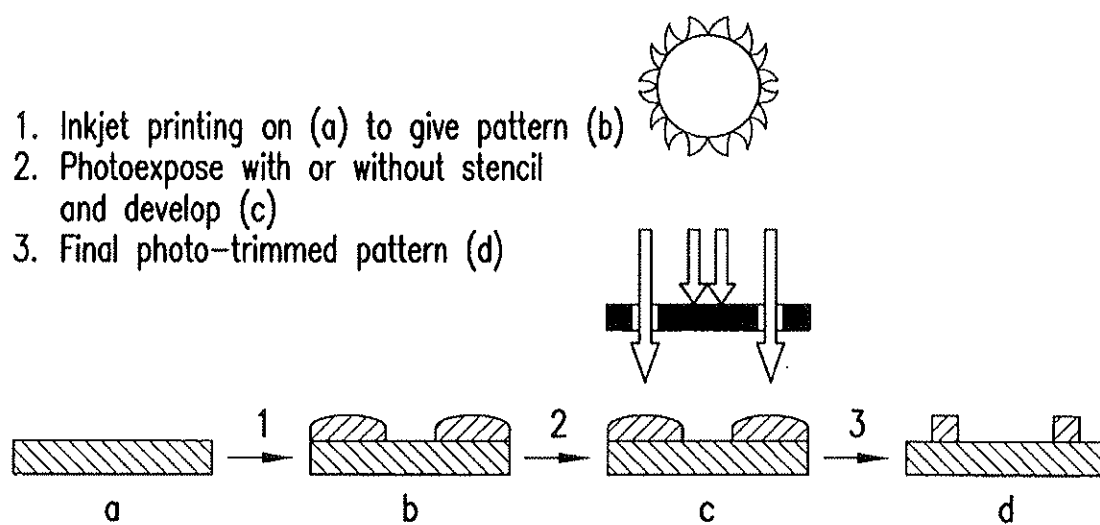


FIG. 1

2/9

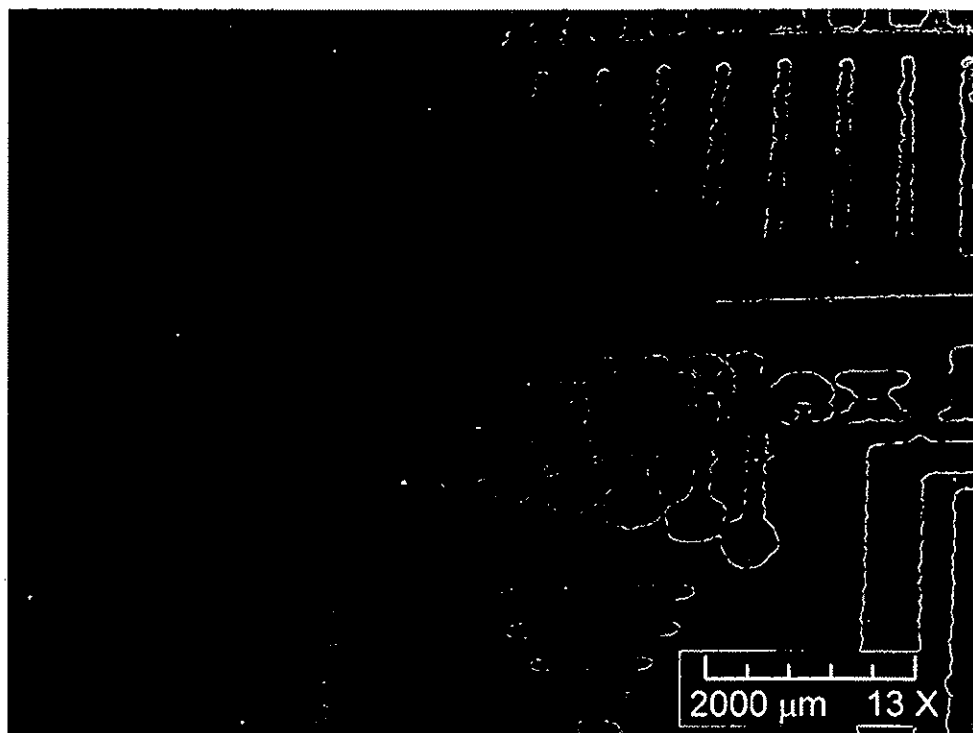


FIG.2

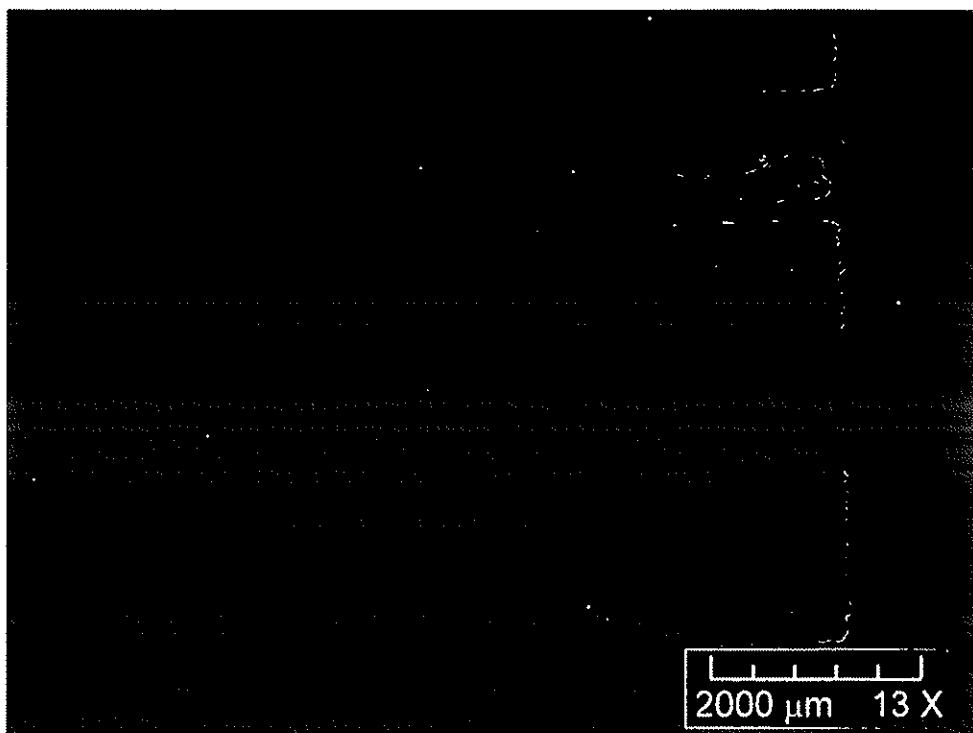


FIG.3

3/9

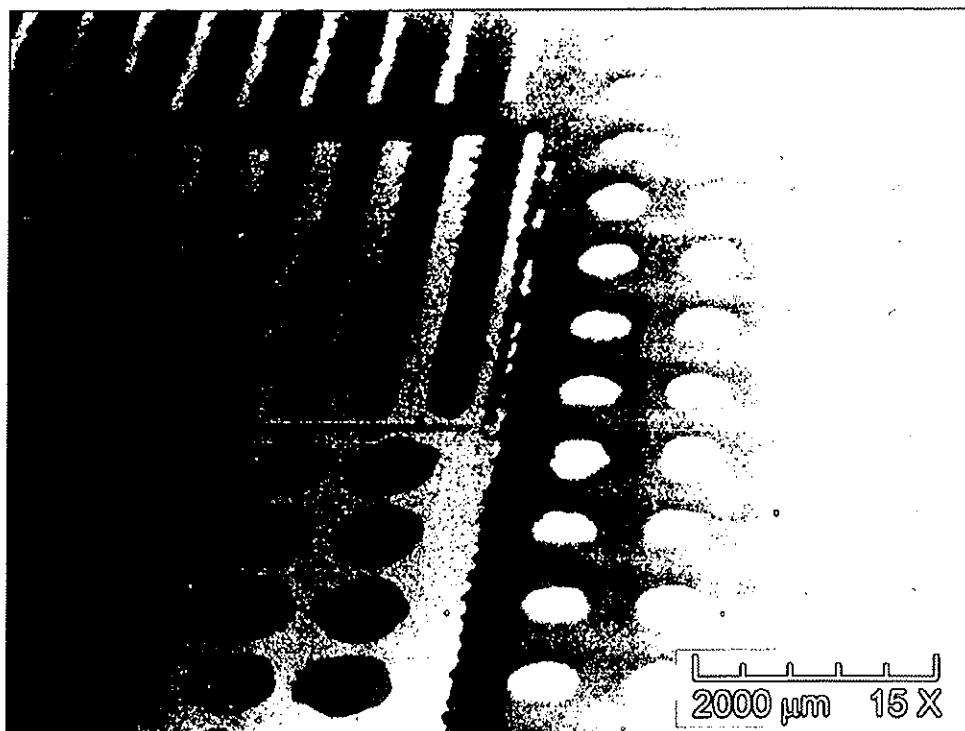


FIG.4

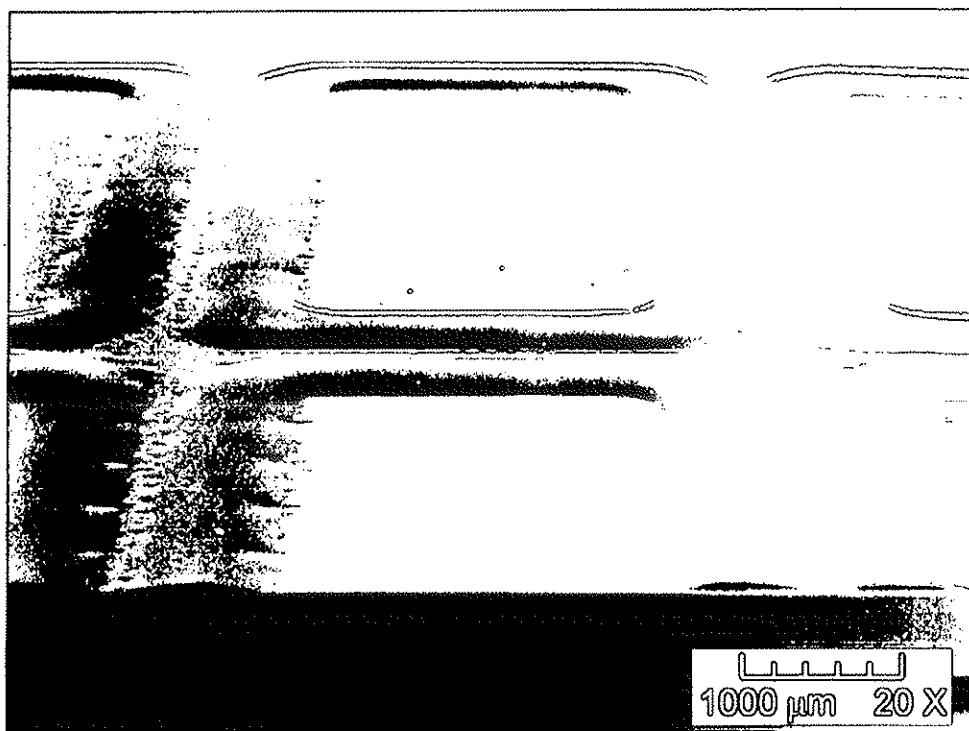


FIG.5

4/9

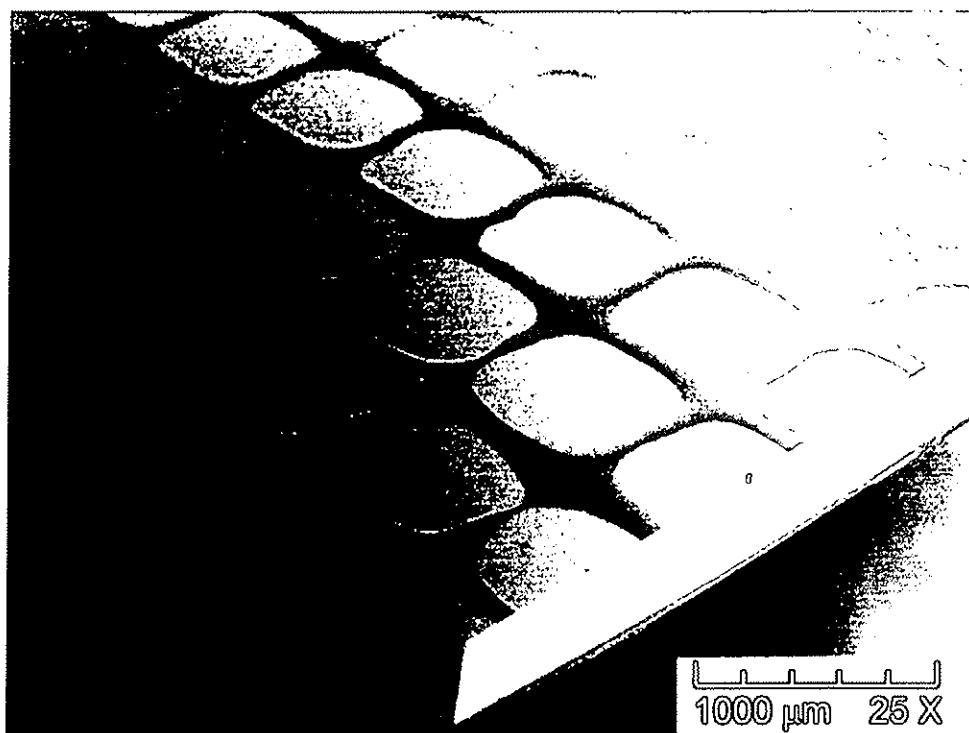


FIG.6

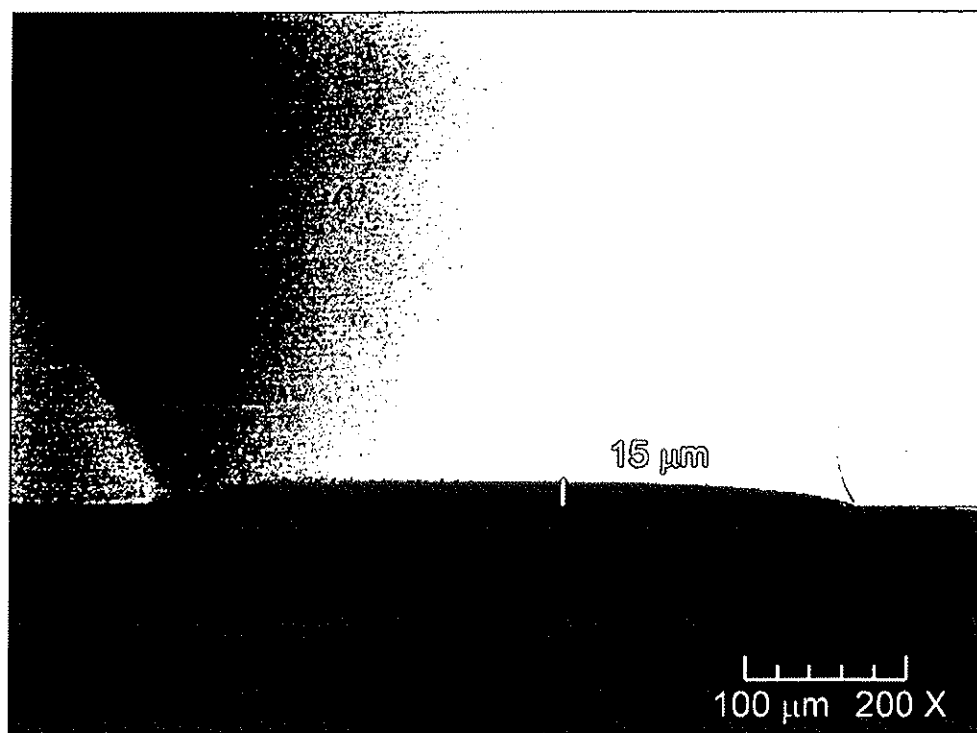


FIG.7

SUBSTITUTE SHEET (RULE 26)

5/9

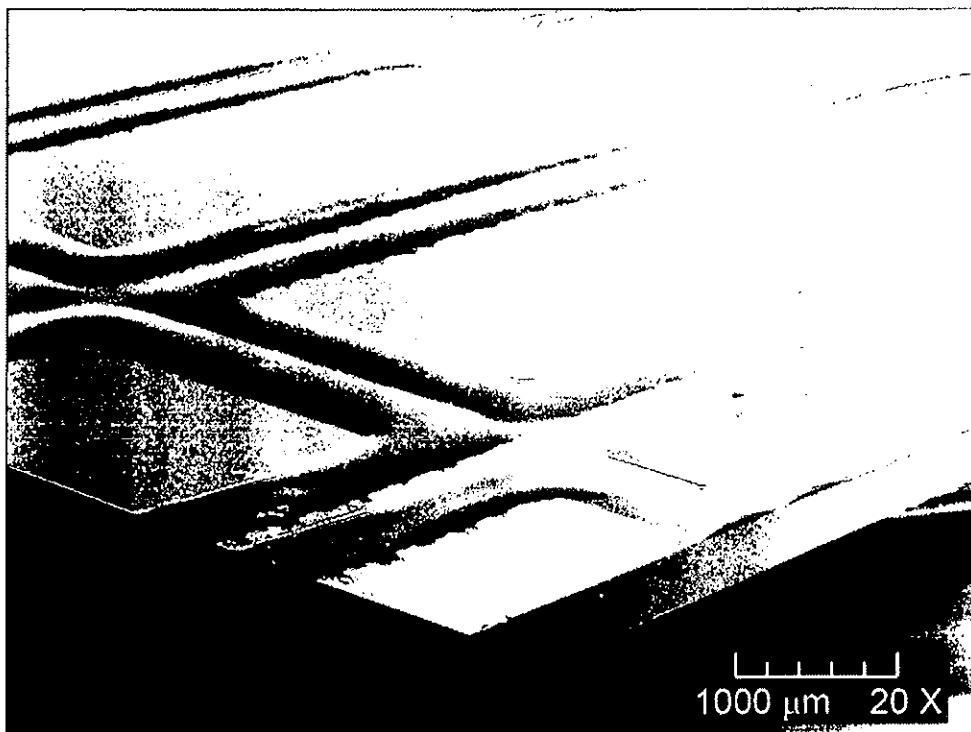


FIG.8

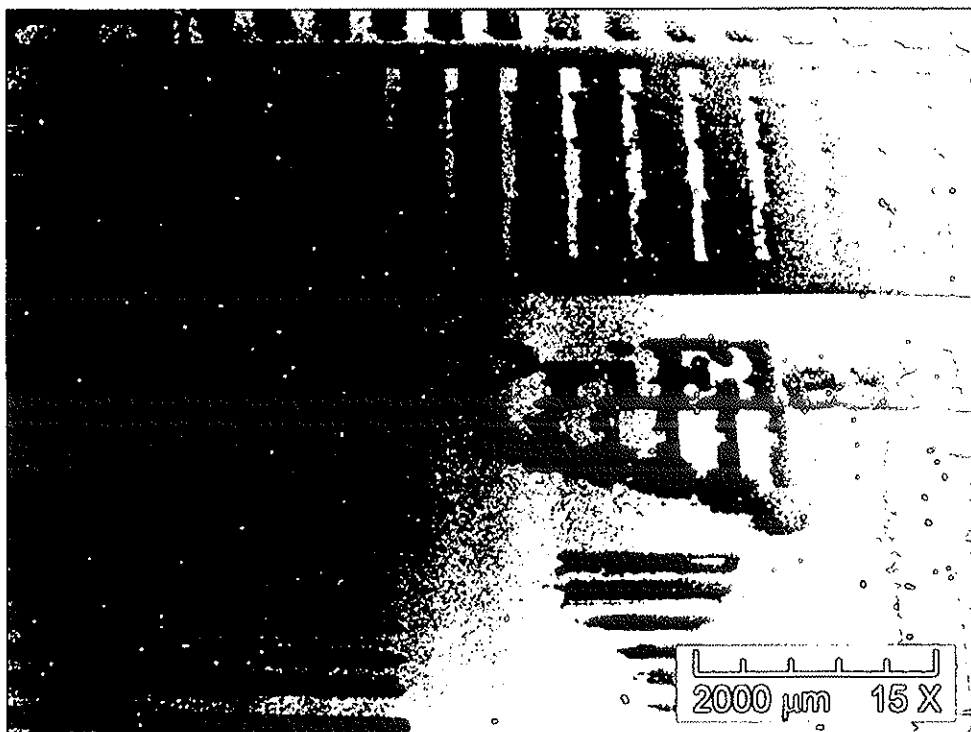


FIG.9

6/9

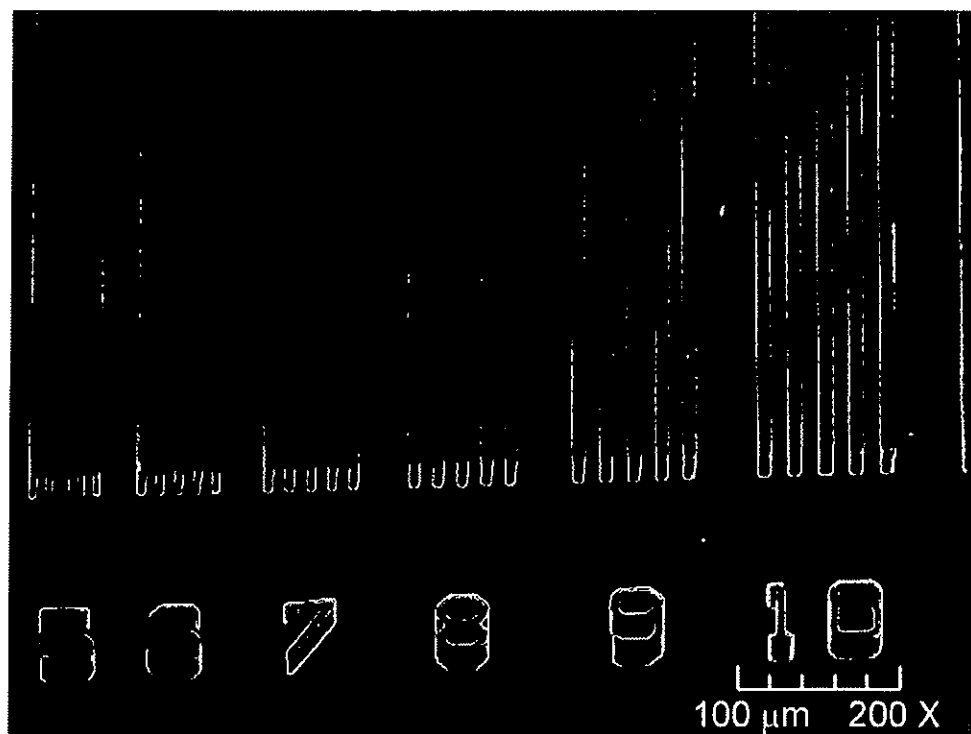


FIG. 10

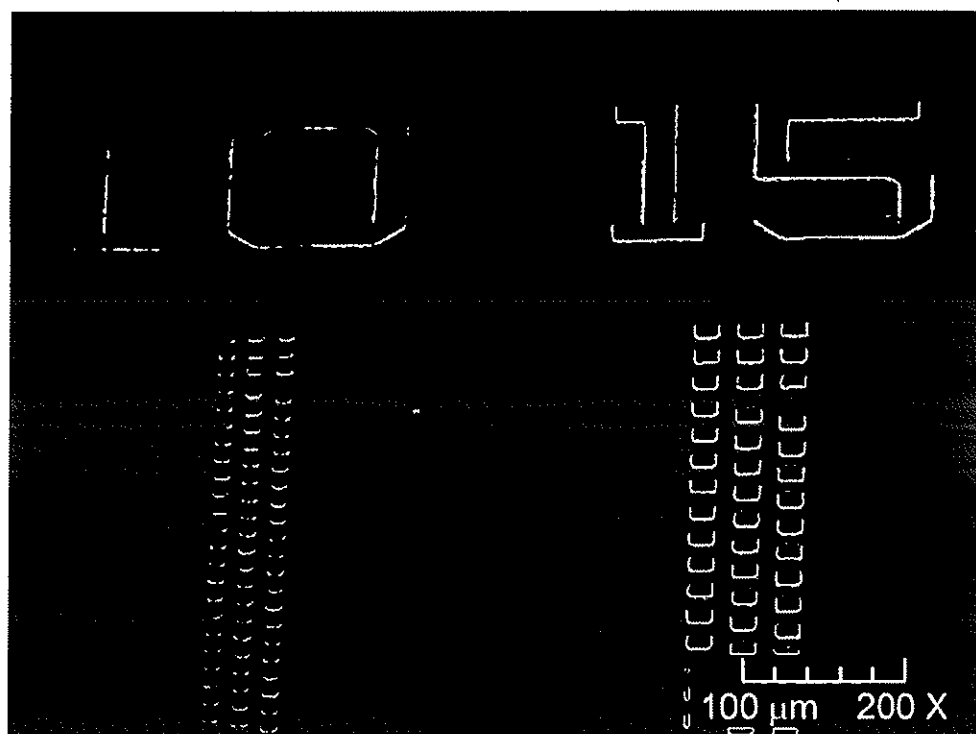


FIG. 11

7/9

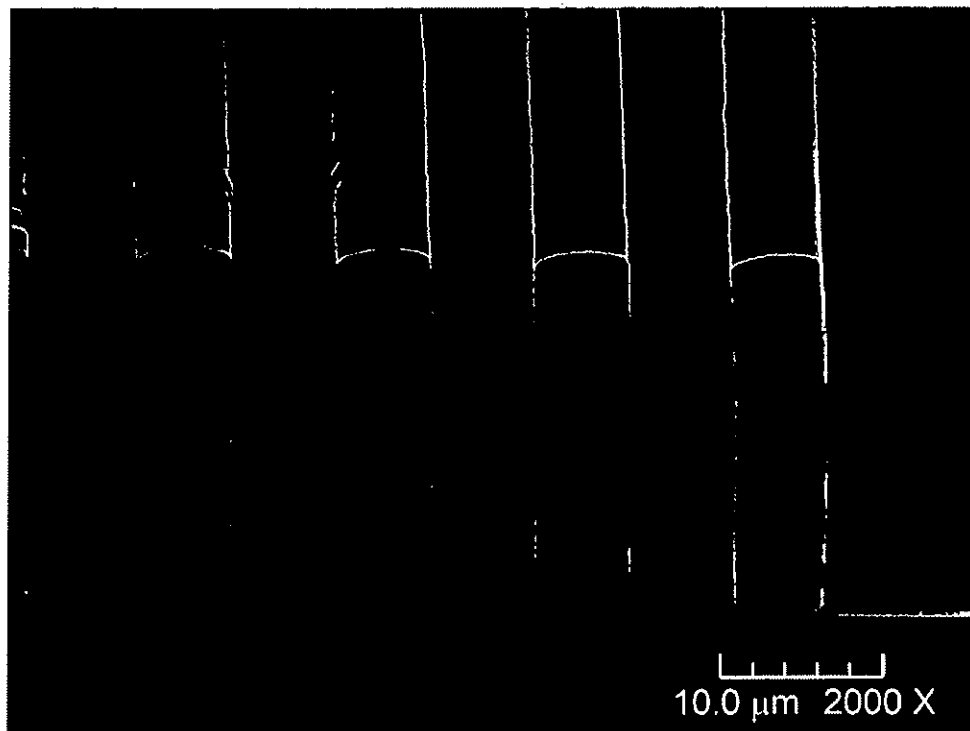


FIG.12

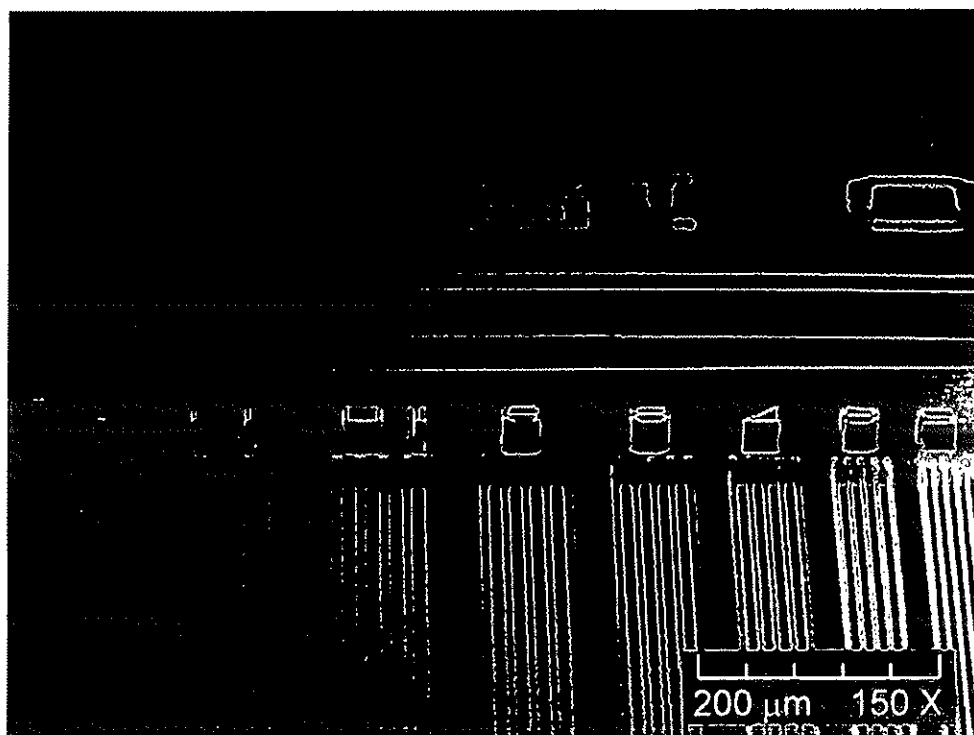


FIG.13

8/9

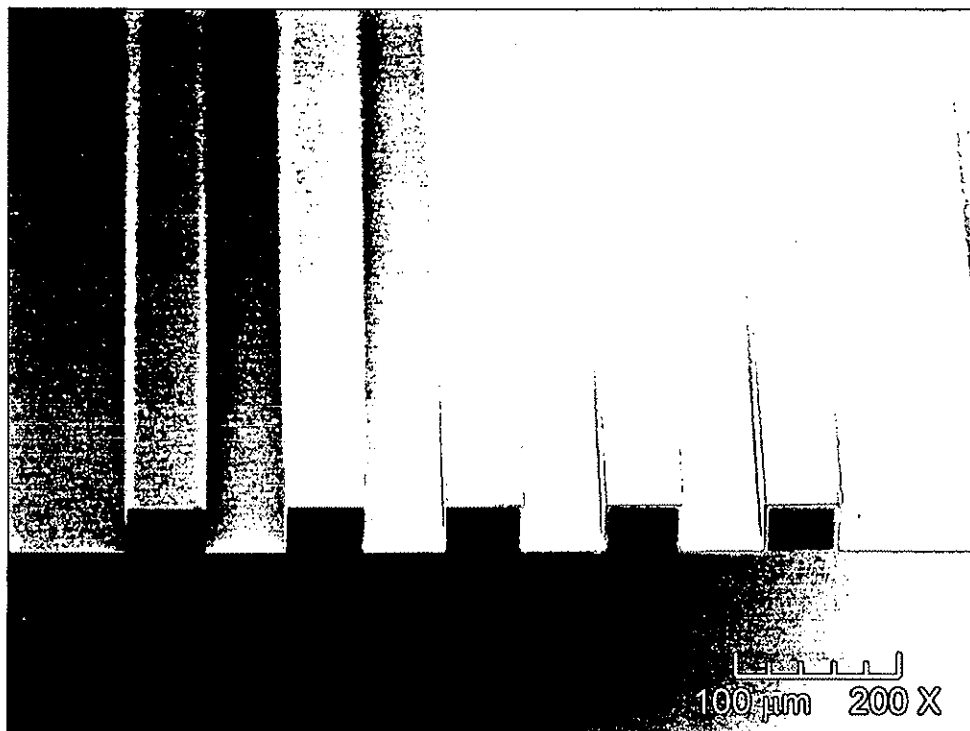


FIG.14

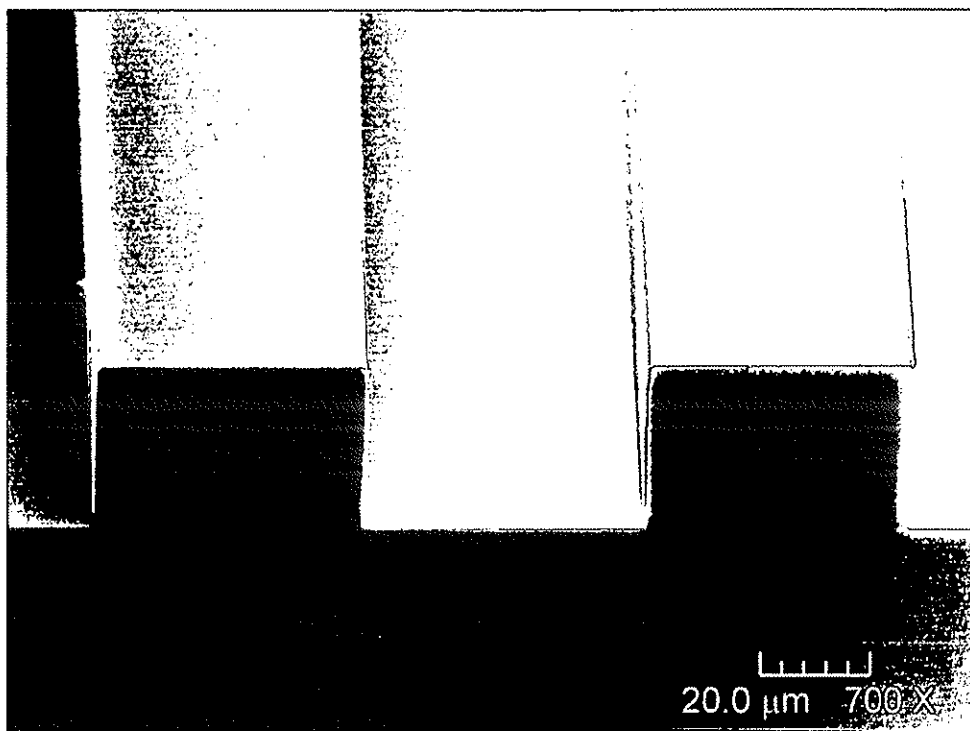


FIG.15

Lift-Off Process, Option 1



1. PMGI ink is deposited



2. UV or thermally cross-linkable ink is deposited.



3. PMGI is dissolved in aqueous base developer.



4. Metal is deposited.

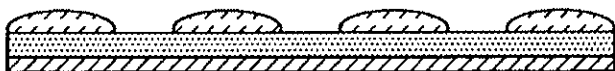


5. Cross-linked ink is removed/lifted-off.

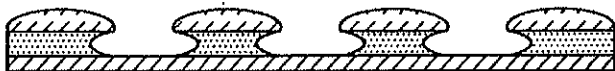
Lift-Off Process, Option 2



1. PMGI ink is deposited



2. UV or thermally cross-linkable ink is deposited.



3. PMGI is dissolved in aqueous developer creating lift-off profile.



4. Metal is deposited.



5. Removal/lifted-off.

Underlayer

PMGI Ink - cure 110 °C for 1 min.

Top Layer

Epoxy Ink - cure 110 °C for 1 min.

Development Time - ~1 min.

2.38% TMAH Developer

FIG.16